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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09/464,297	12/15/1999	SHELDON ARONOWITZ	99-039	7342
LSI Logic Co			EXAMINER	
1551 McCarthy Blvd. M/S: D-106 Patent Department Milpitas, CA 95035			BROWN, CHARLOTTE A	
			ART UNIT	PAPER NUMBER
			1765	6
		•	DATE MAILED: 07/31/2002	

Please find below and/or attached an Office communication concerning this application or proceeding.



Office Action Summary

Application No. 09/464,297

Applicant(s)

Aronowitz et al.

Examiner

Charlotte A. Brown

Art Unit

1765

	• •	on the cover sheet with the correspondence address		
	for Reply	TO TUDIES OF MONTHING PROM		
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.				
- Extens	sions of time may be available under the provisions of 37 CFR 1.136 (a). In	no event, however, may a reply be timely filed after SIX (6) MONTHS from the		
- If the p - If NO p - Failure - Any re	g date of this communication. period for reply specified above is less than thirty (30) days, a reply within the period for reply is specified above, the maximum statutory period will apply a to reply within the set or extended period for reply will, by statute, cause the ply received by the Office later than three months after the mailing date of the dipatent term adjustment. See 37 CFR 1.704(b).	and will expire SIX (6) MONTHS from the mailing date of this communication. he application to become ABANDONED (35 U.S.C. § 133).		
Stạtus				
1) 💢	Responsive to communication(s) filed on Aug 17, 2	2001		
2a) 💢	This action is FINAL . 2b) ☐ This act	tion is non-final.		
3) 🗆	Since this application is in condition for allowance ϵ closed in accordance with the practice under Ex particles.	except for formal matters, prosecution as to the merits is arte Quayle, 1935 C.D. 11; 453 O.G. 213.		
Disposi	ition of Claims			
4) 💢	Claim(s) <u>1-23</u>	is/are pending in the application.		
۵	la) Of the above, claim(s)	is/are withdrawn from consideration.		
5) 🗆	Claim(s)	is/are allowed.		
6) 💢	Claim(s) <u>1-23</u>	is/are rejected.		
7) 🗆	Claim(s)	is/are objected to.		
8) 🗆	Claims	are subject to restriction and/or election requirement.		
Applica	ation Papers			
9)□	The specification is objected to by the Examiner.			
10)	The drawing(s) filed on is/are	e a) \square accepted or b) \square objected to by the Examiner.		
	Applicant may not request that any objection to the d	frawing(s) be held in abeyance. See 37 CFR 1.85(a).		
11)		is: a) approved b) disapproved by the Examiner.		
	If approved, corrected drawings are required in reply t			
12)	The oath or declaration is objected to by the Exami	iner.		
Priority	under 35 U.S.C. §§ 119 and 120			
13)	Acknowledgement is made of a claim for foreign pr	riority under 35 U.S.C. § 119(a)-(d) or (f).		
a) 🗆	☐ All b)☐ Some* c)☐ None of:			
	1. Certified copies of the priority documents have	e been received.		
;	2. Certified copies of the priority documents have	e been received in Application No		
	application from the International Burea			
*Se	ee the attached detailed Office action for a list of the	a certified copies not received.		
14)	Acknowledgement is made of a claim for domestic			
' a) □	The translation of the foreign language provisional			
15)	Acknowledgement is made of a claim for domestic	priority under 35 U.S.C. §§ 120 and/or 121.		
Attachme				
_	otice of References Cited (PTO-892)	4) Interview Summary (PTO-413) Paper No(s).		
_	tice of Draftsperson's Patent Drawing Review (PTO-948)	5) Notice of Informal Patent Application (PTO-152)		
3) Info	ormation Disclosure Statement(s) (PTO-1449) Paper No(s).	6) Other:		

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DETAILED ACTION

1. Applicant has provided evidence in this file showing that the invention was owned by, or

subject to an obligation of assignment to, the same entity as LSI Logic Corporation at the time

this invention was made. Accordingly, Puchner et al. (US 6,156,620) is disqualified as prior art

through 35 U.S.C. 102(e), (f) or (g) in any rejection under 35 U.S.C. 103(a) in this application.

However, this applied art additionally qualifies as prior art under another subsection of 35 U.S.C.

102 and accordingly is not disqualified as prior art under 35 U.S.C. 103(a).

Applicant may overcome the applied art either by a showing under 37 CFR 1.132 that the

invention disclosed therein was derived from the inventor of this application, and is therefore, not

the invention "by another", or by antedating the applied art under 37 CFR 1.131.

2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness

rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person

having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the

manner in which the invention was made.

3. Claims 1-23 are rejected under 35 U.S.C. 103(a) as being unpatentable over. Puntambekar

et al. (US 5,714,037).

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Puntambekar discloses a method for improving adhesion between various materials utilized in the fabrication of integrated circuits. A plasma etcher is provided. A silicon oxide film is provided over the substrate. The surface of the silicon oxide film is treated with a nitrogen plasma in a reactive ion etching mode in a plasma etcher. The nitrogen treatment is a two-step process. Step 1 is an initialization step necessary to strike the plasma. In Step 2, the silicon dioxide film is treated with 100% nitrogen plasma at a flow rate of approximately 200 sccm in a plasma etcher operating at a high DC bias at approximately 950 volts or greater. This reads on the applicant's limitation of maintaining a bias on an electrode in the etching chamber during the exposure of the oxide surface to the nitrogen plasma to control the flow of components of the nitrogen plasma toward the substrate. The optional parameters of the etcher can be varied. During the treatment, the temperature of the lower electrode of the etcher is maintained in the range of 35-38°C and the temperature of the upper electrode is maintained around approximately 20°C.

Although Puntambekar does not teach a method whereby a fixed thickness of silicon oxide will be removed from the oxide surface with the oxide thickness removed dependent upon the power level of the bias on the electrode in the etching chamber, he does teach that the process conditions can be varied for maintaining the rf bias power for during the exposure of the semiconductor substrate to a nitrogen plasma. It is the examiner's position that a person having ordinary skill in the art would have found it obvious to modify Puntambekar by varying the power level of the rf bias in order to remove a fixed thickness of silicon oxide in order to produce an expected result.

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4. Applicant's arguments filed August 17, 2001 have been fully considered but they are not

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persuasive.

In traversing the rejection based on the combination of Puchner and Puntambekar, the

applicant states that the Puchner et al. reference is assigned to LSI Corporation, the assignee of

the present patent application. The applicant argues that the Puchner reference does not qualify as

prior art under 35 U.S.C 103 (c). The Examiner agrees. Therefore, the Puncher is no longer cited

as prior art.

The applicant also states that since the Puntambeker reference is only relied upon for the

placement of a semiconductor substrate on an electrode as a substrate support, the claims should

be allowable over the cited references. However, it is the Examiner's position that Puntambeker

teaches the limitations of exposing an oxide surface to a nitrogen plasma and a step of maintaining

an rf bias on the semiconductor substrate.

5. The prior art made of record and not relied upon is considered pertinent to applicant's

disclosure. (US 6,136,211)

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Conclusion

6. THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time

policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE

MONTHS from the mailing date of this action. In the event a first reply is filed within TWO

MONTHS of the mailing date of this final action and the advisory action is not mailed until after

the end of the THREE-MONTH shortened statutory period, then the shortened statutory period

will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR

1.136(a) will be calculated from the mailing date of the advisory action. In no event, however,

will the statutory period for reply expire later than SIX MONTHS from the mailing date of this

final action.

7. Any inquiry concerning this communication from the Examiner should be directed to

Charlotte A. Brown whose telephone number is (703) 305-0727. The Examiner can normally be

reached during the hours of 9:00AM to 6:30PM.

The fax phone numbers for the organization where this application or proceeding is

assigned are 703-872-9310 for regular communications and 703-872-9311 for After Final

communications.

CAB

July 25, 2002

ROBERT KUNEMUND
RIMARY PATENT FXAMINER

PRIMARY PATENT EXAMINE

A.U. 117